

**PRESS RELEASE**

**MacDermid Alpha to Present Next Generation Assembly & Interconnect Technologies for 3D In-Mold Electronics at TechBlick 2022**

(Waterbury, CT USA) – October 3<sup>rd</sup>, 2022 – MacDermid Alpha Electronics Solutions, a global supplier of integrated solutions from our Circuitry, Assembly and Semiconductor divisions, will present the technical paper '*Next Generation Assembly and Interconnect Technologies for Smart Structures and Functional Surfaces*' at the TechBlick Conference and Expo taking place October 12-13 in Eindhoven, Netherlands.



**The Future of Electronics Reshaped**

**Title: Next Generation Assembly and Interconnect Technologies for Smart Structures and Functional Surfaces**

**Speaker: Rahul Raut - Portfolio Manager, FFPE**

**Date/Time: 12th October/3.20pm**

**Location: Eindhoven, Netherlands**



Rahul Raut, Global Portfolio Manager – FFPE at MacDermid Alpha, will discuss the key building blocks of 3D smart structural platforms, covering novel film substrates which include multifunctional PC substrates for In-Mold Electronics, highly conductive and formable Silver Inks, high performance formable Dielectrics, formable structural and electrically conducting adhesives (ECAs) and formable encapsulants. The performance and capability of integrated multi-layer stacks that can be thermoformed and then injection molded to produce smart, interactive 3D structures will be presented, as well as the ability of these integrated 3D structures to meet or exceed the stringent reliability requirements for automotive, medical, white goods and other demanding applications.

MacDermid Alpha's suite of electronic inks, coatings and film materials are designed to meet the unique functional and reliability requirements for In-Mold Electronics, Functional HMI (Human-Machine Interface) Surfaces and Adhesively Laminated FPCs. We offer a comprehensive suite of fully compatible materials, processing and applications support for our films, electronic inks & adhesives to produce 3D Smart, Functional and 3D Automotive HMI Structures. Our film capabilities

include functional and decorative solutions, such as heat-stabilized Autostat PET and XtraForm PC films. Additionally, our electronic materials portfolio provides integrated electronics capabilities for the printed circuit board and semiconductor industries. We provide an inter-compatible comprehensive solution of electronic materials, films and processes.

Rahul Raut will present the technical paper on Wednesday 12<sup>th</sup> October at 3.20pm during the TechBlick Conference. MacDermid Alpha will also participate in the TechBlick expo, visit us at tabletop number 38 to discuss our latest technologies for 3D In-Mold Electronics. To register for TechBlick please visit: <https://www.techblick.com>

To learn more about MacDermid Alpha's range of films, electronics inks and adhesives for 3D smart and functional structures please visit: [macdermidalpha.com](http://macdermidalpha.com)

**About MacDermid Alpha Electronics Solutions:**

Through the innovation of specialty chemicals and materials under our Alpha, Compugraphics, Electrolube, Kester, and MacDermid Enthone brands, MacDermid Alpha Electronics Solutions provides solutions that power electronics interconnection. We serve all global regions and every step of device manufacturing within each segment of the electronics supply chain. The experts in our Assembly Solutions, Semiconductor Solutions, and Circuitry Solutions divisions collaborate in design, implementation, and technical service to ensure success for our partner clients. Our solutions enable our customers' manufacture of extraordinary electronic devices at high productivity and reduced cycle time.